

Product Specification

CUSTOMER: _____

DESCRIPTION: _____

RF TRANSFORMER

MNC P/N: _____

RFT-128SG

REVISION: _____

X0

CUSTOMER P/N: _____

ISSUED DATE: _____

2016-08-17

PHOTO OF
PRODUCT: _____

WEIGHT: _____

0.09g





PREPARED BY	CHECKED BY	APPROVED BY
Wen Lee	Sonny Zhang	Simon Zhang

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CHANGE RECORD

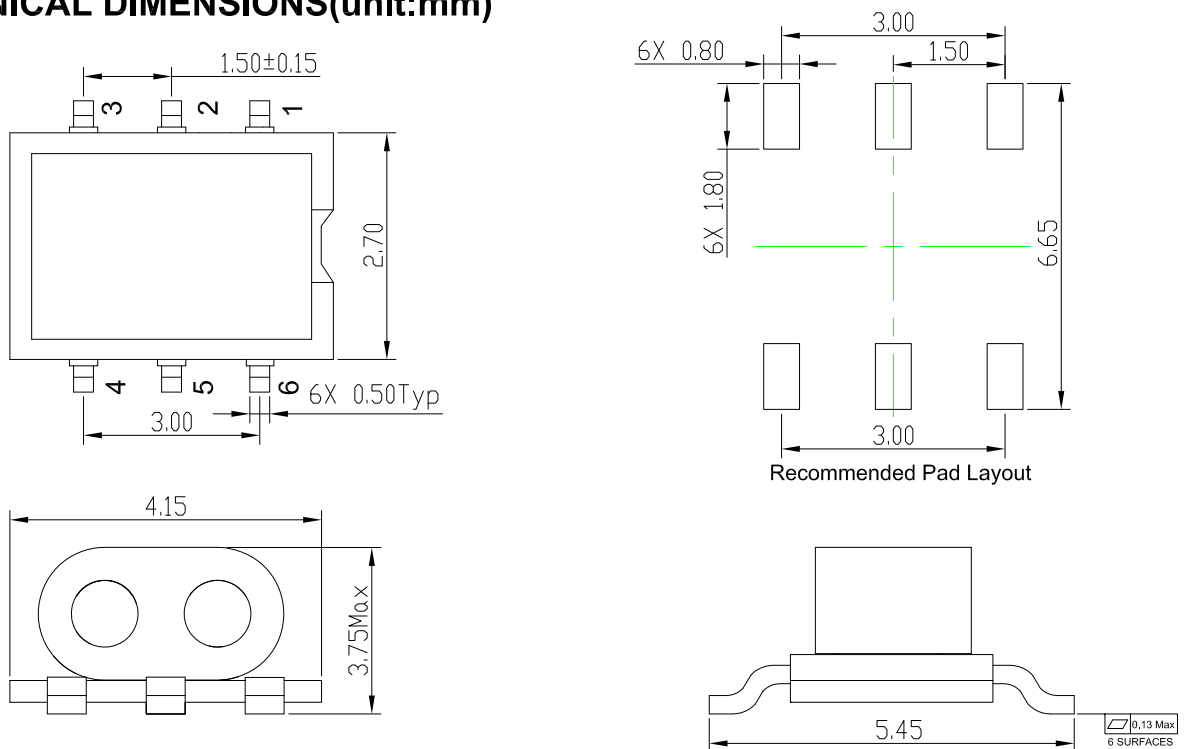
REV.	DESCRIPTION (Content or Reason For Change)	DATE	REVISER
X0	INITIAL RELEASE	2016-08-17	Wen Lee

-  RF Transformer
-  Operating temperature range: -40°C to +85°C
-  Storage temperature range: -55°C to +125°C
-  RoHS compliant

Electrical Specifications @25°C, Z ₀ =100Ω						
Part Number	Turns Ratio	Insertion Loss	HI-POT	DC Current	RF Power	Frequency
		Pri:Sec(1-3:6-4)	1-100 MHz	Pri to Sec(1-3 to 6-4)	30mA Max	250mW Max
RFT-128SG	1.25CT:1CT±5%	1.0dB Max	1500Vrms 2S, 0.5mA			

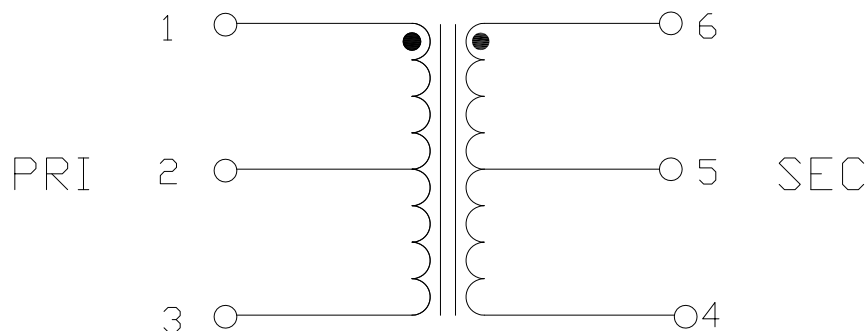
Note: Insertion Loss is referenced to mid-band loss 0.5dB typ. Measure back to back.

MECHANICAL DIMENSIONS(unit:mm)



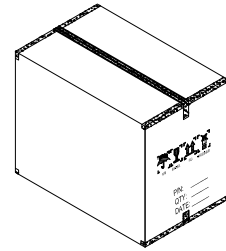
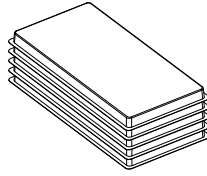
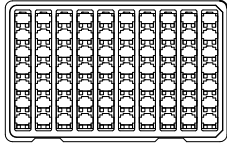
Unless otherwise specified all tolerances are: ±0.25 mm

SCHEMATIC



PACKING:

Tray:

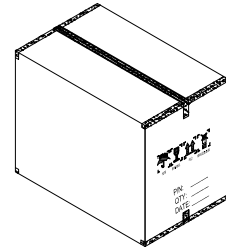
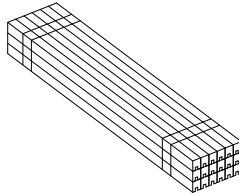


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_____ PCS Per Tray

_____ PCS Per Carton

Tube:

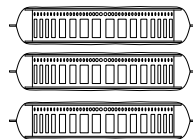
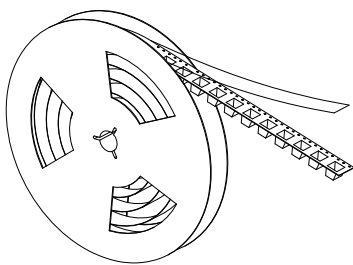


Q'ty

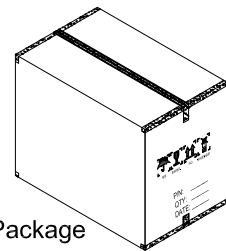
_____ PCS Per Tube

_____ PCS Per Carton

Reel:



Vacuumize Package



Q'ty

 1200 PCS Per Reel

 12000 PCS Per Carton

MOISTURE SENSITIVE LEVEL:

- 1. Level:1
- 2.Shelf Life:Unlimited
- 3.Storage Condition:<=30℃/85% RH

RECOMMENDED SOLDERING PROFILE:

1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

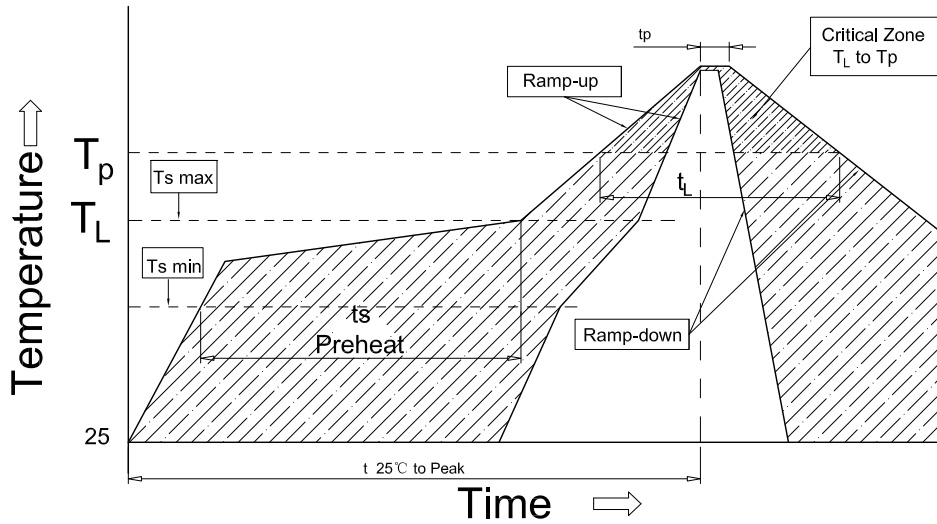


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3°C/second max	3°C/second max
Preheat		
-Temperature Min (T _{smin})	100°C	150°C
-Temperature Max (T _{smax})	150°C	200°C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time maintained above:	183°C	217°C
-Temperature (T _l)	60-150 seconds	60-150 seconds
-Time (t _l)		
Peak/Classification Temperature(T _p)	See IPC/JEDEC J-STD-020Table 4-1	See IPC/JEDEC J-STD-020Table 4-2
Time within 5°C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

Note: All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process: Reflow soldering
Solder Paste: Sn96.5Ag3.0Cu0.5
Silkscreen thickness: 0.15mm Min.

2. Wave soldering profile

